Linx Cleaning Conferences

Monday, August 31, 2020

Time	Session	Format	Speaker	Organization
9:00 - 9:10 AM CT	**Introductions, Welcome, Conference Overview**	Live	**Mark Thirsk**	
9:10 - 9:45 AM	Impact of COVID-19 and outlook for Surface Prep and Cleans	Live + Q&A	Mike Corbett	Linx Consulting
9:45 - 10:20 AM	The Risks to the Consensus Economic Outlook - and What It Might Mean for Semiconductors	Live + Q&A	Duncan Meldrum	Hilltop Economics
10:20 - 10:45 AM	Wet Etch Challenges and Innovations Driving Nano-Electronics Scaling	Live + Q&A	Nabil Mistkawi	Samsung - SAS
10:45 - 11:10 AM	Wet Cleans Research and Development for Advanced Semiconductor Technologies	Live + Q&A	Brown Peethala	IBM
11:10 - 11:35 AM	Understanding the Hidden Source of Next Excursion	Live + Q&A	Dhiman Bhattacharyya	Global Foundries
11:35 AM - 12:00 PM	Future Post-CMP Cleaning Challenges	Live + Q&A	Mike White	Entegris
12:00 - 12:30 PM	Virtual Chat			
	Wrap Up / Additional Questions / Adjourn - Day 1 End		**Organizers**	

Prerecorded Presentations

Time	Session	Format	Speaker	Organization
	Post CMP Cleans Evolution and Defect Improvement Approaches		Katrina Mikhaylichenko	Applied Materials
	Challenges and Opportunities of Wet Clean Processes to Enable System Scaling for AI Era		Hiroaki Takahashi	Screen

Tuesday, September 1, 2020

Time	Session	Format	Speaker	Organization
9:00 - 9:15 AM CT	**Introductions, Day 1 Welcome, Conference Overview**	Live	**Mark Thirsk** **Joel Barnett**	
9:15 - 9:50 AM	**Keynote: Monolithic Heterogeneous 3D Integration of Germanium PMOS with Si NMOS for Enabling Moore's Law Scaling and Performance**	Live + Q&A	**Willy Rachmady**	**Intel**
9:50 - 10:10 AM	Selective Ge removal from SiGe surface for Si-cap-free SiGe passivation	Live + Q&A	Kurt Wostyn	IMEC
10:10 - 10:30 AM	Wetting of deep hydrophilic nanoholes by aqueous solutions	Live + Q&A	Guy Vereecke	IMEC
10:30 - 10:50 AM	Defect Reduction for Post Silicon Nitride Deposition Clean in MOL Sector	Live + Q&A	Bing Wu	Global Foundries
10:50 - 11:10 AM	Wet-chemical Cleaning of Cobalt and Molybdenum for Advanced Interconnects	Live + Q&A	Quoc Toan Le	IMEC
11:10 AM - 12:30 PM	**Break / Networking Reception / Poster Session**			
12:30 - 12:35 PM	**Wrap Up / Additional Questions / Adjourn - Day 2 End**		**Organizers**	

Wednesday, September 2, 2020

Time	Session	Format	Speaker	Organization
9:00 - 9:10 AM CT	**Day 3 Welcome**	Live	**Mark Thirsk** **Joel Barnett**	
9:10 - 9:45 AM	**Invited: CMOS Device Architecture Evolution and its Impact on Surface Preparation and Cleaning for N2 and Beyond**	Recorded	**Naoto Horiguchi**	**IMEC**
9:45 - 10:05 AM	The zeta potential of conductive material surfaces: challenges and solutions	Live + Q&A	Thomas Luxbacher	Anton Paar
10:05 - 10:25 AM	Particle analysis of unpatterned wafers with UNISERS	Live + Q&A	Altun (Ali) Ozhan	UNISERS
10:25 - 10:45 AM	Surface preparation of Niobium for Superconducting Qubit applications	Live + Q&A	Antoine Pacco	IMEC

10:45 - 11:05 AM	Advanced Purification and Defect Removal from Isopropyl Alcohol	Live + Q&A	Makonnen Payne	Pall
11:05 AM - 12:25 PM	**Break / Networking Reception / Poster Session**			
12:25 - 12:30 PM	**Wrap Up / Additional Questions / Adjourn - Day 3 End**		**Organizers**	

Prerecorded Presentations

Controlled Isotropic Etches for Gate-All-Around (GAA) Device Architectures	Yusuke Muraki	TEL
Nanosheet RMG: Metal Gate and Interface Dipole Patterning	Yusuke Oniki	IMEC
Selective TiN vs HfOx Etch with BARC Compatibility for 5 and 3nm Node Applications	Sherman Hsu	Avantor
Trimming Clean using SAPS Megasonic Technology on Xtacking 3D NAND	Sally Ann Henry	ACM Research
Wet Etching of SiO2 Film in Narrow Spaces	Dai Ueda	Screen
Study on PVA Brush Particle Loading and its Conditioning during Post CMP Cleaning	Hwi-Won Cho	Hanyang University
Mechanisms of Colloidal Ceria Contamination and Cleaning during Oxide Post-CMP Cleaning	Samrina Sahir	Hanyang University
Development of a Non-Contact Chemical Concentration Monitor	Tatsuya Nakahara	Horiba
Optimization of wet etching process to remove replacement polysilicon gate	Parth Vaidya	Global Foundries

Tuesday, September 1, 2020 Poster Session

Development of Co/Cu Wet-etch Chemistries for BEoL application	Yi-Chia Lee	EMD
Development of HA-free stripper for photoresist/ARC removal	Lili Wang	EMD
Monitoring of Fluoride in Semiconductor Cleaning Chemicals	Chuannan Bai	ECI
Isotropic Etches for Nanosheet Device Integration – Wet or Dry?	Oniki Yusuke	IMEC
Evaluating wet and dry particle deposition methods on semiconductor substrates for nanoparticle removal efficiency testing	Chimaobi Mbanaso	TEL
Challenges for chemical raw material supplies to semiconductor industry and the solutions	Hui Zhou	Huntsman
Using Wafer Edge and Bevel Vapor Phase Decomposition Inductively Coupled Plasma Mass Spectrometry for Defect Reduction in High Volume Semiconductor Manufacturing	Chris Sparks	Air Liquide
Characterization and removal of metallic contamination in process chemicals using Single Nanoparticle ICP-MS	Siddarth Sampath	Entegris
Removal of trace metals from Isopropyl Alcohol	Ashtosh Bhabhe	Entegris